

## **Description**

The XF devices are ultra-low phase noise quartz-based PLL oscillators supporting a large range of frequencies and output interface types. These devices are designed to operate at three different power supplies with several pinout configurations, as well as two operational temperature ranges.

The XF devices can be programmed to generate an output frequency from 15MHz to 2100MHz with a resolution as low as 1Hz accuracy. The configuration capability of this family of devices allows for fast delivery times for both sample and large production orders.

Parts are for one time programming (OTP) at the factory for a fixed frequency application, or can be field programmable using I2C, based on system needs (see notes under Pin Descriptions).

# **Typical Applications**

- FOM Gear Box
- Data centers
- 10G / 40G / 100G / 400G Ethernet

## **Features**

Output types: LVDS, LVPECL, CML

Frequency range: 15MHz to 2100MHz

Output type: HCSL

Frequency range: 15MHz to 725MHz

Supply voltage options: 1.8V, 2.5V, or 3.3V

Phase jitter (12kHz to 20MHz): 120fs typical

Package options:

• 5.0 × 3.2 mm

• 3.2 × 2.5 mm

• 2.5 × 2.0 mm

Operating temperatures and frequency stability:

-40°C to +85°C, ±25ppm

-40°C to +105°C, ±50ppm

# **Pin Assignments**

Figure 1. 2.5 × 2.0 mm Package

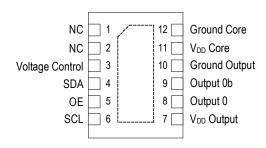
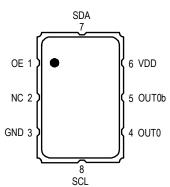


Figure 2. 5.0 × 3.2 mm and 3.2 × 2.5 mm Packages





# **Pin Descriptions**

Table 1. Pin Descriptions for 2.5 × 2.0 mm Package

Pin Number	Pin Name	Description
1	NC	No connect.
2	NC	No connect.
3	Voltage Control <sup>2</sup>	Voltage control for VCXO option.
4	SDA <sup>1</sup>	Serial data.
5	OE	Output enable.
6	SCL <sup>1</sup>	Serial clock.
7	V <sub>DD</sub> Output	Supply voltage.
8	Output 0	Output 0.
9	Output 0b	Complementary output 0.
10	Ground Output	Connect to ground.
11	V <sub>DD</sub> Core	Supply voltage.
12	Ground Core	Connect to ground.
13	EPAD (dotted area shown in Pin Assignments diagram)	Connect to ground (required for heat dissipation).

<sup>&</sup>lt;sup>1</sup> Pins 4 and 6 are no connect for non-I2C applications.

See Ordering Information (VCXO) for more details.

Table 2. Pin Descriptions for 5.0 × 3.2 mm and 3.2 × 2.5 mm Packages

Pin#	Pin Name	Description
1	OE	Output Enable (0 = output disabled, pulled high internally)
2	NC	No connect
3	GND	Connect to ground
4	OUT0	Output
5	OUT0b	Complementary output
6	V <sub>DD</sub>	Supply voltage
7	SDA <sup>1</sup>	Serial data
8	SCL <sup>1</sup>	Serial clock

<sup>&</sup>lt;sup>1</sup> Pins 7 and 8 are no connect for non-I2C applications.

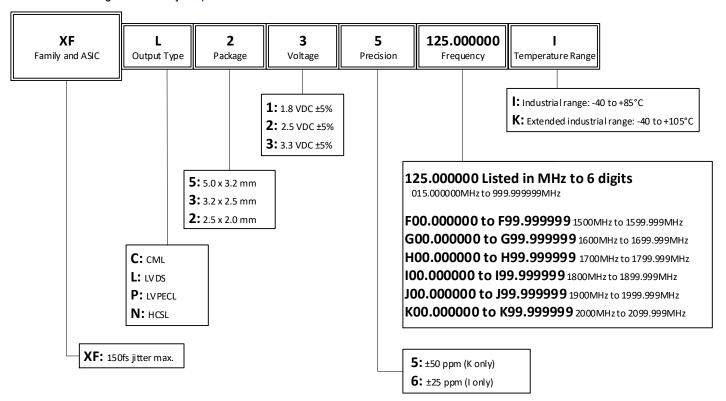
See Ordering Information (VCXO) for more details.

<sup>&</sup>lt;sup>2</sup> Pin 3 is no connect for non-analog VCXO applications.

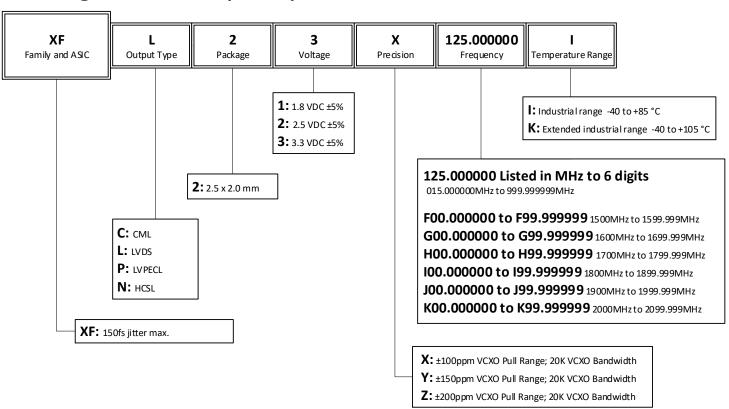


## **Ordering Information (XO)**

Custom Part Configuration Utility: https://www.renesas.com/customxo



## **Ordering Information (VCXO)**





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## **Absolute Maximum Ratings**

Stresses above the ratings listed below can cause permanent damage to the device. These ratings, which are standard values for Renesas commercially rated parts, are stress ratings only. Functional operation of the device at these or any other conditions above those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods can affect product reliability. Electrical parameters are guaranteed only over the recommended operating temperature range. Thermal characteristics, in actual applications, should be assessed case by case to guarantee junction temperature does not exceed 125°C.

**Table 3. Absolute Maximum Ratings** 

Item	Rating				
$V_{DD}$		-0.5V to +3.8V			
E/D	-0.5V to +3.8V				
Storage Temperature		-55°C to 125°C			
Maximum Junction Temperature		125°C			
Theta J <sub>A</sub> <sup>1</sup>	$\frac{97.0 \text{ °C/W}}{62.2 \text{ °C/W}} = 3.2 \times 2.5 \text{ mm (LNG8)} \frac{131.47 \text{ °C/W}}{92.89 \text{ °C/W}} = 5.0 \times 3.2 \text{ mm (LXG8)} \frac{13}{92.89 \text{ °C/W}} = \frac{13}{12.47 \text{ °C/W}} = \frac{13}$				
Theta J <sub>B</sub> <sup>1</sup>	62.2 °C/W	92.89 °C/W 97.42 °C/W			

<sup>&</sup>lt;sup>1</sup> Thermal characteristics are based on simulation in standard condition.

## **ESD Compliance**

#### **Table 4. ESD Compliance**

Human Body Model (HBM)	2000V
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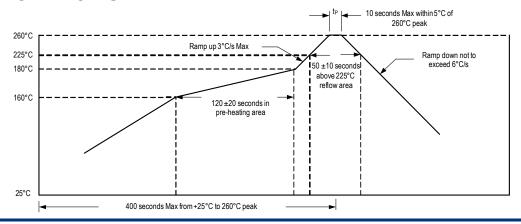
# **Mechanical Testing**

Table 5. Mechanical Testing \*

Parameter	Test Method
Mechanical Shock	Half-sine wave with 0.3ms 3000G. X, Y, Z each direction 1 time.
Mechanical Vibration	Frequency: 10 to 55MHz amplitude: 1.5mm. Frequency: 55–2000Hz peak value: 20G. Duration time: 4H for each X,Y,Z axis; total 12hours.
High Temp Operating Life (HTOL)	1000 hours at 125°C (under power).
Hermetic Seal	Gross leak (air leak test). Fine leak (Helium leak test) He-pressure: 6kgf/cm² 2 hours.

<sup>\*</sup> MSL level does not apply.

## **Solder Reflow Profile**





## **DC Electrical Characteristics**

Note for all DC Electrical Characteristics tables: A pull-up resistor from  $V_{DD}$  to OE enables output when pin 5 is left open.

**Table 6. 3.3V IDD DC Electrical Characteristics** 

 $V_{DD}$  = 3.3V ±5%,  $T_A$  = -40°C to +85°C, -40°C to +105°C, typical at 156.25MHz.

Symbol	Parameter	Output Type	Conditions	Minimum	Typical	Maximum	Units
		LVDS	15MHz to 400MHz.	_	59	67	
	Current Consumption	LVDS	400MHz to 2.1GHz.	_	_	85	mA
I <sub>DD</sub>		LVPECL	15MHz to 212.5MHz.	_	84	94	
			212MHz to 400MHz.	_	_	110	
			400MHz to 2.1GHz.	_	_	110	
		HCSL	15MHz to 725MHz.	_	74	83	
		CML	15MHz to 2.1GHz.	_	45	61	

#### **Table 7. 2.5V IDD DC Electrical Characteristics**

 $V_{DD}$  = 2.5V ±5%,  $T_A$  = -40°C to +85°C, -40°C to +105°C, typical at 156.25MHz.

Symbol	Parameter	Output Type	Conditions	Minimum	Typical	Maximum	Units
		LVDC	15MHz to 400MHz.	_	59	66	
		LVDS	400MHz to 2.1GHz.	_	_	85	- mA
I <sub>DD</sub>	Current Consumption	LVPECL	15MHz to 156.25MHz.	_	84	94	
			156.25MHz to 400MHz.	_	_	110	
			400MHz to 2.1GHz.	_	_	110	
		HCSL	15MHz to 400MHz.	_	_	95	
			400MHz to 725MHz.	_	74	82	
		CML	15MHz to 2.1GHz.	_	54	61	

#### **Table 8. 1.8V IDD DC Electrical Characteristics**

 $V_{DD}$  = 1.8V ±5%,  $T_A$  = -40°C to +85°C, -40°C to +105°C, typical at 156.25MHz.

Symbol	Parameter	Output Type	Conditions	Minimum	Typical	Maximum	Units
	Current Consumption	LVDS	15MHz to 400MHz.	_	59	66	mA
			400MHz to 2.1GHz.	_	_	85	
I <sub>DD</sub>		LVPECL	15MHz to 250MHz.	_	84	93	
			250MHz to 2.1GHz.	_	_	110	
		HCSL	15MHz to 400MHz.	_	_	95	
			400MHz to 725MHz.	_	74	81	
		CML	15MHz to 2.1GHz.	_	54	61	•



#### **Table 9. LVCMOS DC Electrical Characteristics**

 $V_{DD}$  = 3.3V, 2.5V, 1.8V ±5%,  $T_A$  = -40°C to +85°C, -40°C to +105°C, typical at 156.25MHz.

Symbol	Parameter	Conditions	Minimum	Typical	Maximum	Units
V <sub>IH</sub>	Input High Voltage (OE pin only)	V <sub>DD</sub> = 3.3V, 2.5V, 1.8V ±5%	0.7 × V <sub>DD</sub>	_	V <sub>DD</sub> + 0.3	V
V <sub>IL</sub>	Input Low Voltage (OE pin only)	V <sub>DD</sub> = 3.3V, 2.5V, 1.8V ±5%	GND - 0.3	_	0.3 × V <sub>DD</sub>	V

#### **Table 10. LVDS DC Electrical Characteristics**

 $V_{DD}$  = 3.3V, 2.5V, 1.8V ±5%,  $T_A$  = -40°C to +85°C, -40°C to +105°C, typical at 156.25MHz.

Symbol	Parameter	Conditions	Minimum	Typical	Maximum	Units
V <sub>OD</sub>	Differential Output Voltage	V <sub>DD</sub> = 3.3V, 2.5V, 1.8V ±5%	0.30	0.44	0.60	
		V <sub>DD</sub> = 3.3V ±5%	1.11	1.26	1.41	W
Vos	Output Offset Voltage	V <sub>DD</sub> = 2.5V ±5%	1.08	1.25	1.41	V
		V <sub>DD</sub> = 1.8V ±5%	0.75	0.88	1.01	

#### **Table 11. LVPECL DC Electrical Characteristics**

 $V_{DD}$  = 3.3V, 2.5V, 1.8V ±5%,  $T_A$  = -40°C to +85°C, -40°C to +105°C, typical at 156.25MHz.

Symbol	Parameter	Conditions	Minimum	Typical	Maximum	Units
		$V_{DD} = 3.3V \pm 5\%$ .	2.28	2.49	2.72	
V <sub>OH</sub>	Output High Voltage	V <sub>DD</sub> = 2.5V ±5%.	1.52	1.69	1.87	
		V <sub>DD</sub> = 1.8V ±5%.	0.83	0.96	1.11	V
V <sub>OL</sub>	Output Low Voltage	V <sub>DD</sub> = 3.3V ±5%.	1.68	1.84	2.01	V
		V <sub>DD</sub> = 2.5V ±5%.	0.92	1.04	1.17	
		V <sub>DD</sub> = 1.8V ±5%.	0.19	0.30	0.42	

#### **Table 12. HCSL DC Electrical Characteristics**

 $V_{DD}$  = 3.3V, 2.5V, 1.8V ±5%,  $T_A$  = -40°C to +85°C, -40°C to +105°C, typical at 156.25MHz.

Symbol	Parameter	Conditions	Minimum	Typical	Maximum	Units
		V <sub>DD</sub> = 3.3V ±5%.	0.78	0.92	1.07	
V <sub>OH</sub>	Output High Voltage	$V_{DD} = 2.5V \pm 5\%$ .	0.74	0.88	1.03	V
		V <sub>DD</sub> = 1.8V ±5%.	0.67	0.81	0.95	V
V <sub>OL</sub>	Output Low Voltage	_	-0.06	0.07	0.20	



#### **Table 13. CML DC Electrical Characteristics**

 $V_{DD} = 3.3V, 2.5V, 1.8V \pm 5\%, T_A = -40$ °C to +85°C, -40°C to +105°C, typical at 156.25MHz.

Symbol	Parameter	Conditions	Minimum	Typical	Maximum	Units
		V <sub>DD</sub> = 3.3V ±5%.	3.09	3.26	3.43	
V <sub>OH</sub>	Output High Voltage	$V_{DD} = 2.5V \pm 5\%$ .	2.33	2.46	2.59	V
		$V_{DD} = 1.8V \pm 5\%$ .	1.66	1.76	1.85	
		$V_{DD} = 3.3V \pm 5\%$ .	2.70	2.85	3.00	
$V_{OL}$	Output Low Voltage	$V_{DD} = 2.5V \pm 5\%$ .	1.95	2.06	2.17	V
		$V_{DD} = 1.8V \pm 5\%$ .	1.30	1.37	1.45	

#### Table 14. DC Electrical Characteristics - Leakage Current

 $V_{DD}$  = 3.3V, 2.5V, 1.8V ±5%,  $T_A$  = -40°C to +85°C, -40°C to +105°C, typical at 156.25MHz.

Symbol	Parameter	Input	Conditions	Minimum	Typical	Maximum	Units
		OE		-5	0.81	5	
I <sub>IH</sub>	Input Leakage High	SCLK	$V_{DD} = 3.3V \pm 5\%$ .	-5	1.36	5	μA
		SDATA		-5	1.44	5	
		OE		-20	-17.44	-14	
I <sub>IL</sub>	Input Leakage Low	SCLK	$V_{DD} = 3.3V \pm 5\%$ .	-37	-33.49	-30	μA
		SDATA		-20	-17.02	-14	

## **AC Electrical Characteristics**

Notes for all AC Electrical Characteristics tables:

- 1. A pull-up resistor from  $V_{DD}$  to OE enables output when pin 5 is left open.
- 2. Installation should include a  $0.01\mu F$  bypass capacitor placed between  $V_{DD}$  and GND to minimize power supply line noise.

#### **Table 15. 3.3V AC Electrical Characteristics**

 $V_{DD} = 3.3V \pm 5\%$ ,  $T_A = -40$ °C to +85°C, -40°C to +105°C.

Symbol	Parameter	Test Condition	Minimum	Typical	Maximum	Units
F	Output Fraguency Dange	LVDS, LVPECL, CML.	15	_	2100	MHz
Г	Output Frequency Range	HCSL.	15	_	725	IVITZ
	Fraguency Stability	Temperature = -40°C to +85°C.	_	_	±25	ppm
	Frequency Stability	Temperature = -40°C to +105°C.	_	_	±50	ppm
	Frequency Tolerance (25°C)	Temperature = 25°C.	_	_	±15	ppm
	Aging (1st year)	T <sub>A</sub> = 25°C.	_	_	±3	ppm
	Aging (10 years)	T <sub>A</sub> = 25°C.	_	_	±10	ppm



## Table 15. 3.3V AC Electrical Characteristics (Cont.)

 $V_{DD}$  = 3.3V ±5%,  $T_A$  = -40°C to +85°C, -40°C to +105°C.

Symbol	Parameter	Test Co	ondition	Minimum	Typical	Maximum	Units
		LVDS.	Differential.	_	100	_	
	Output Load	LVPECL.	V <sub>DD</sub> - 2.0V.	_	50	_	Ω
		HCSL.	To GND.	_	50	_	
T <sub>ST</sub>	Start-up Time	Output valid time after \ specified level.	/ <sub>DD</sub> meets minimum	_	5	_	ms
		LVDS.		_	299	400	
4	Output Rise Time	LVPECL.	20% – 80%,	_	287	400	20
$t_R$	Output Rise Time	HCSL.	156.25MHz	_	306	400	ps
		CML		_	301	400	
		LVDS.		_	279	400	
	Output Fall Time	LVPECL.	80% – 20%,	_	274	400	
t <sub>F</sub>	Output Fall Time	HCSL.	156.25MHz	_	284	400	ps
		CML		_	279	400	
		LVDS.	156.25MHz	45	_	55	
0	Output Clock Duty Cycle	LVPECL.	156.25MHz	45	_	55	- - -
$O_{DC}$		HCSL.	156.25MHz	45	_	55	
		CML	156.25MHz	45	_	55	
$T_{OE}$	Output Enable/Disable Time	_	_	_	1	_	ms



### **Table 16. 2.5V AC Electrical Characteristics**

 $V_{DD}$  = 2.5V ±5%,  $T_A$  = -40°C to +85°C, -40°C to +105°C.

Symbol	Parameter	Test C	Test Condition		Typical	Maximum	Units
F	Output Fraguency Dange	LVDS, LVPECL, CML.		15	_	2100	MHz
Г	Output Frequency Range	HCSL.		15	_	725	IVI□Z
	Fraguency Ctability	Temperature = -40°C t	o +85°C.	_	_	±25	ppm
	Frequency Stability	Temperature = -40°C t	o +105°C.	_	_	±50	ppm
	Frequency Tolerance (25°C)	Temperature = 25°C.		_	_	±15	ppm
	Aging (1st year)	T <sub>A</sub> = 25°C.		_	_	±3	
	Aging (10 years)	T <sub>A</sub> = 25°C.		_	_	±10	
		LVDS.	Differential.	_	100	_	
	Output Load	LVPECL.	V <sub>DD</sub> - 2.0V.	_	50	_	Ω
		HCSL.	To GND.	_	50	_	
T <sub>ST</sub>	Start-up Time	Output valid time after specified level.	V <sub>DD</sub> meets minimum	_	5	_	ms
		LVDS.		_	303	400	
4	Output Rise Time	LVPECL.	20% – 80%,	_	292	400	no
t <sub>R</sub>	Output Rise Time	HCSL.	156.25MHz	_	310	400	ps
		CML		_	304	400	
		LVDS.		_	282	400	
4	Output Fall Time	LVPECL.	80% – 20%,	_	278	400	no
t <sub>F</sub>	Output Fail Time	HCSL.	156.25MHz	_	288	400	ps
		CML		_	281	400	
		LVDS.	156.25MHz	45	_	55	
0	Output Clock Duty Cycle	LVPECL.	156.25MHz	45	_	55	- %
O <sub>DC</sub>	Output Glock Duty Cycle	HCSL.	156.25MHz	45	_	55	
		CML	156.25MHz	45	_	55	
T <sub>OE</sub>	Output Enable/Disable Time	_	_	_	1	_	ms



### **Table 17. 1.8V AC Electrical Characteristics**

 $V_{DD}$  = 1.8V ±5%,  $T_A$  = -40°C to +85°C, -40°C to +105°C.

Symbol	Parameter	Test	Condition	Minimum	Typical	Maximum	Units
F	Output Fraguency Dange	LVDS, LVPECL, CML.		15	_	2100	MHz
г	Output Frequency Range	HCSL.		15	_	725	IVITZ
	Fraguency Stability	Temperature = -40°C	C to +85°C.	_	_	±25	ppm
	Frequency Stability	Temperature = -40°C	C to +105°C.	_	_	±50	ppm
	Frequency Tolerance (25°C)	Temperature = 25°C		_	_	±15	ppm
	Aging (1st year)	T <sub>A</sub> = 25°C.		_	_	±3	ppm
	Aging (10 years)	T <sub>A</sub> = 25°C.		_	_	±10	ppm
	Output Lood	LVDS.	Differential.	_	100	_	0
	Output Load	LVPECL, HCSL.	To GND.	_	50	_	Ω
T <sub>ST</sub>	Start-up Time	Output valid time after specified level.	Output valid time after V <sub>DD</sub> meets minimum specified level.		5	_	ms
		LVDS.		_	311	450	
	Output Dies Time	LVPECL.	20% – 80%,	_	312	450	
t <sub>R</sub>	Output Rise Time	HCSL.	156.25MHz	_	316	450	ps -
		CML		_	313	450	
		LVDS.		_	290	450	
	Output Fall Time	LVPECL.	80% – 20%,	_	297	450	
t <sub>F</sub>	Output Fall Time	HCSL.	156.25MHz	_	294	450	ps
		CML		_	289	450	
		LVDS.	156.25MHz	45	_	55	- %
0	Output Clock Duty Cycle	LVPECL.	156.25MHz	45	_	55	
O <sub>DC</sub>	Output Glock Duty Cycle	HCSL.	156.25MHz	45	_	55	7/0
		CML	156.25MHz	45	_	55	1
T <sub>OE</sub>	Output Enable/Disable Time	_	_	_	1	_	ms

### **Table 18. Phase Jitter Characteristics**

 $V_{DD}$  = 3.3V, 2.5V, 1.8V ±5%,  $T_A$  = -40°C to +85°C, -40°C to +105°C.

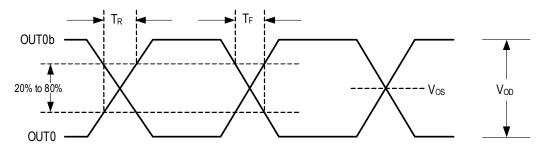
Symbol	Parameter	Conditions	Minimum	Typical	Maximum	Units
	Phase Jitter (12kHz – 20MHz)	250.00MHz	_	115	_	fsec
f		312.50MHz	_	125	_	fsec
<sup>T</sup> JITTER		625.00MHz	_	123	_	fsec
		644.53MHz	_	120	_	fsec



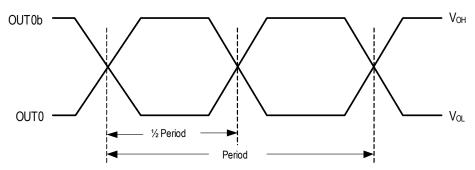
# **Output Waveforms**

## Figure 3. LVDS/LVPECL/HCSL/CML Output Waveforms

## Output Levels /Rise Time/Fall Time Measurements



## **Oscillator Symmetry**





# **Termination for 3.3V LVPECL Outputs**

The clock layout topology shown below is a typical termination for LVPECL outputs. The two different layouts mentioned are recommended only as guidelines.

The differential output is a low impedance follower output that generate ECL/LVPECL compatible outputs. Therefore, terminating resistors (DC current path to ground) or current sources must be used for functionality. These outputs are designed to drive  $50\Omega$  transmission lines. Matched impedance techniques should be used to maximize operating frequency and minimize signal distortion. Figure 4 and Figure 5 show two different layouts which are recommended only as guidelines. Other suitable clock layouts may exist and it would be recommended that the board designers simulate to guarantee compatibility across all printed circuit and clock component process variations.

Figure 4. 3.3V LVPECL Output Termination

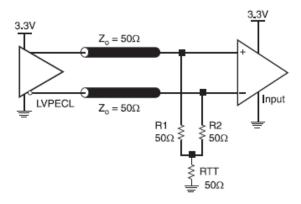
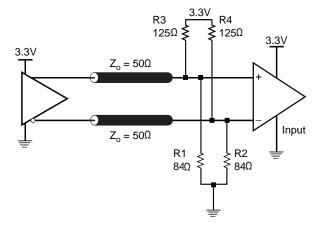


Figure 5. 3.3V LVPECL Output Termination





# **Termination for 2.5V LVPECL Outputs**

Figure 6 and Figure 7 show examples of termination for 2.5V LVPECL driver. These terminations are equivalent to terminating  $50\Omega$  to  $V_{CCO} - 2V$ . For  $V_{CCO} = 2.5V$ , the  $V_{CCO} - 2V$  is very close to ground level. The R3 in Figure 8 can be eliminated and the termination is shown in Figure 7.

Figure 6. 2.5V LVPECL Driver Termination Example

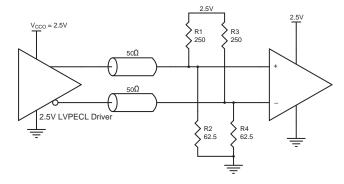


Figure 7. 2.5V LVPECL Driver Termination Example

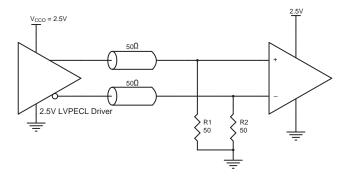
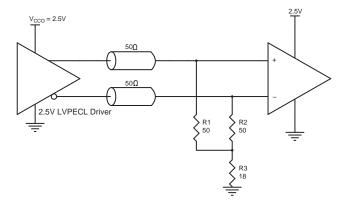


Figure 8. 2.5V LVPECL Driver Termination Example





## **LVDS Driver Termination**

For a general LVDS interface, the recommended value for the termination impedance ( $Z_T$ ) is between  $90\Omega$  and  $132\Omega$ . The actual value should be selected to match the differential impedance ( $Z_0$ ) of your transmission line. A typical point-to-point LVDS design uses a  $100\Omega$  parallel resistor at the receiver and a  $100\Omega$  differential transmission-line environment. In order to avoid any transmission-line reflection issues, the components should be surface mounted and must be placed as close to the receiver as possible. Renesas offers a full line of LVDS compliant devices with two types of output structures: current source and voltage source.

The standard termination schematic as shown in Figure 9 can be used with either type of output structure. Figure 10, which can also be used with both output types, is an optional termination with center tap capacitance to help filter common mode noise. The capacitor value should be approximately 50pF. If using a non-standard termination, it is recommended to contact Renesas and confirm if the output structure is current source or voltage source type. In addition, since these outputs are LVDS compatible, the input receiver's amplitude and common-mode input range should be verified for compatibility with the output.

Figure 9. Standard LVDS Termination

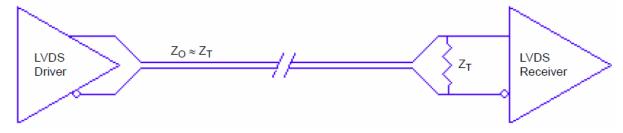
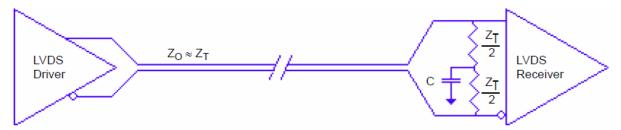


Figure 10. Optional LVDS Termination





## **Recommended Termination for HCSL Outputs**

Figure 11 is the recommended source termination for applications where the driver and receiver will be on a separate PCBs. This termination is the standard for PCI Express<sup>TM</sup> and HCSL output types. All traces should be  $50\Omega$  impedance single-ended or  $100\Omega$  differential. Figure 12 is the recommended termination for applications where a point-to-point connection can be used. A point-to-point connection contains both the driver and the receiver on the same PCB. With a matched termination at the receiver, transmission-line reflections will be minimized. In addition, a series resistor (Rs) at the driver offers flexibility and can help dampen unwanted reflections. The optional resistor can range from  $0\Omega$  to  $33\Omega$ . All traces should be  $50\Omega$  impedance single-ended or  $100\Omega$  differential.

Figure 11. Recommended Source Termination (where the driver and receiver will be on separate PCBs)

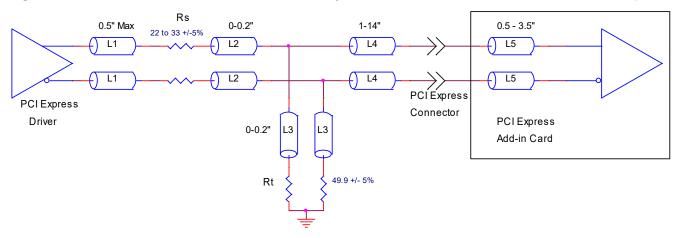
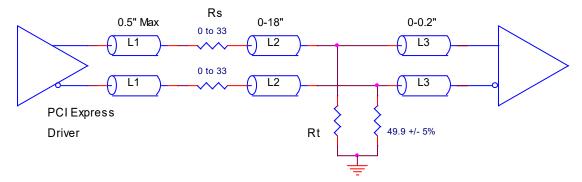


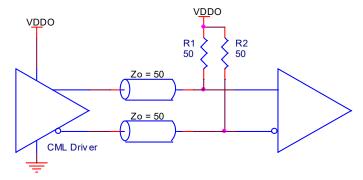
Figure 12. Recommended Termination (where a point-to-point connection can be used)



### **CML Termination**

Figure 13 shows an example of the termination for a CML driver. In this example, the transmission line characteristic impedance is  $50\Omega$ . The R1 and R2  $50\Omega$  matched load terminations are pulled up to VDDO. The matched loads are located close to the receiver.

Figure 13. CML Termination Example





## **Package Outline Drawings**

The package outline drawings are located at the end of this document and are accessible from the links below. The package information is the most current data available and is subject to change without revision of this document.

 $2.5 \times 2.0$  mm package (NJG12)

 $3.2 \times 2.5$  mm package (LNG8)

 $5.0 \times 3.2$  mm package (LXG8)

## **Marking Diagrams**

#### Marking Configuration for the 2.5 × 2.0 mm (NJG12) Package

ABC-YW \$PF\*\*

- Line 1 indicates the following:
  - "ABC" denotes the truncated first three digits of the frequency code (e.g., 156).
  - "-YW" denotes the last digit of the year and week when the part was assembled.
- Line 2 indicates the following:
  - "\$" denotes the mark location code.
  - "PF" denotes the package and frequency codes, where "P" = package code and "F" = frequency code.
  - "\*\*" denotes the sequential lot number.

# Figure 14. Marking Configuration for the 3.2 × 2.5 mm (LNG8) Package (example based on XFL336156.250000I)



- Line 1 denotes the truncated part number as follows:
  - "F" = a combination of the 3rd digit (output type, e.g. "L") and the 5th digit (voltage supply, e.g. "3"), in accordance with the mapping key as follows:

- "xxxxxx" = the first three digits to the left of the decimal point and the last three digits to the left of the decimal point as shown in the above example. This number will vary depending upon the frequency value selected in the orderable part number. (e.g. 156250)).
- Line 2 indicates the following:
  - "YWW" denotes the last digit of the year and week when the part was assembled.
  - "\*\*" denotes the sequential lot number.
  - "\$" denotes the mark location.

# Figure 15. Marking Configuration for the 5.0 $\times$ 3.2 mm (LXG8) Package (example based on XFL526125.000000I)

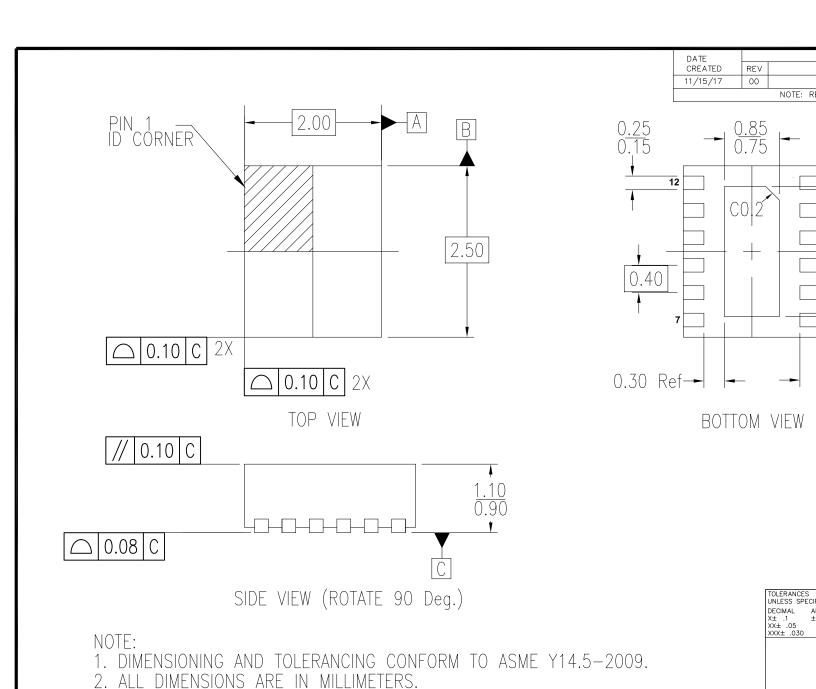


- Line 1 indicates the following:
  - XF = family; "L" = output type; "526" = package, voltage, precision
- Line 2 indicates the following:
  - "125000" = the first three digits to the left of the decimal point and the last three digits to the left of the decimal point as shown in the above example. This number will vary depending upon the frequency value selected in the orderable part number.
- Line 3 indicates the following:
  - "YYWW" denotes the last digits of the year and week when the part was assembled.
  - "\*\*" denotes the sequential lot number.

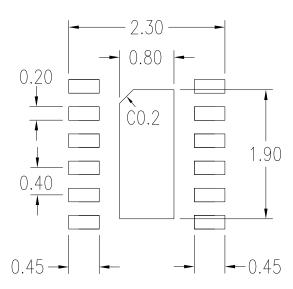


# **Revision History**

Revision Date	Description of Change
<ul> <li>May 10, 2021</li> <li>Updated Package and Precision codes in VCXO Ordering Information table.</li> <li>Moved XO and VCXO Ordering Information tables to follow Pin Descriptions.</li> <li>Updated VCXO Precision options from H, J, and K to X, Y, and Z, updated VCXO bar</li> </ul>	
<ul> <li>March 31, 2021</li> <li>Updated title of Ordering Information table to include (XO).</li> <li>Added a new Ordering Information table for (VCXO).</li> <li>Updated Frequency Tolerance values.</li> </ul>	
February 11, 2021	Added new package options: 5.0 × 3.2 mm and 3.2 × 2.5 mm.
January 6, 2020	Updated notes for pin descriptions.
July 22, 2019	Updated LVDS Differential Output Voltage minimum value from 0.28V to 0.30V.
May 22, 2019	Changed 3.3V, 2.5V, and 1.8V LVPECL current consumption conditions value from 670MHz to 2.1GHz.
April 3, 2019	Initial release.



DATE		
CREATED	REV	
11/15/17	00	
		NOTE: F



RECOMMENDED LAND PATTERN

# NOTES:

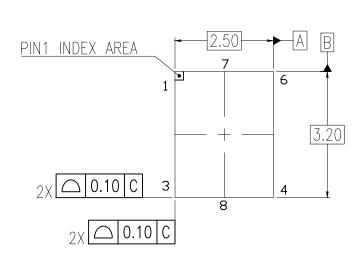
- 1. ALL DIMENSIONS ARE IN mm. ANGLES IN DEGREES.
- 2. TOP DOWN VIEW. AS VIEWED ON PCB.
- 3. LAND PATTERN RECOMMENDATION PER IPC-7351B GENERIC REQUIREMENT FOR SURFACE MOUNT DESIGN AND LAND PATTERN.

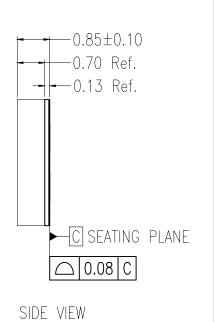
TOLERANCES
UNLESS SPEC
DECIMAL A
X± .1 =
XX± .05
XXX± .030



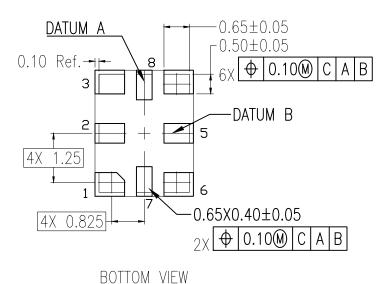
# 8-LGA, Package Outline Drawing

2.50 x 3.20 x 0.85 mm Body, 1.25mm Pitch LNG8D1, PSC-4837-01, Rev 00, Page 1





TOP VIEW



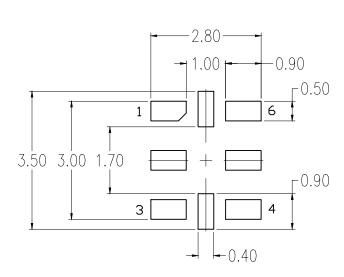
## NOTES:

- 1. DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5-2009
- 2. ALL DIMENSIONS ARE IN MILLIMETERS



# 8-LGA, Package Outline Drawing

2.50 x 3.20 x 0.85 mm Body, 1.25mm Pitch LNG8D1, PSC-4837-01, Rev 00, Page 2



RECOMMENDED LAND PATTERN DIMENSION

## NOTES:

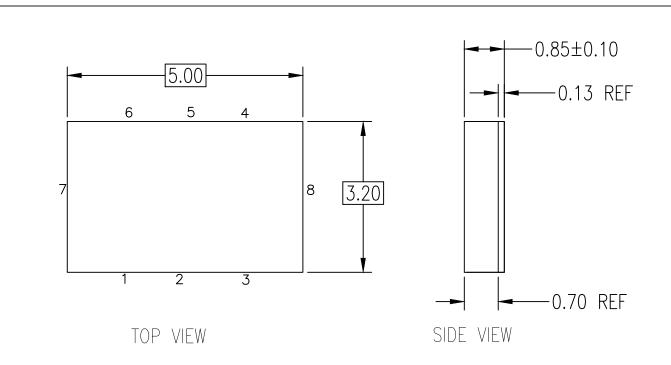
- 1. ALL DIMENSIONS ARE IN MM. ANGLES IN DEGREES
- 2. TOP DOWN VIEW. AS VIEWED ON PCB
- 3. LAND PATTERN RECOMMENDATION PER IPC-7351B GENERIC REQUIREMENT FOR SURFACE MOUNT DESIGN AND LAND PATTERN
- 4. NSMD PATTERN ASSUMED

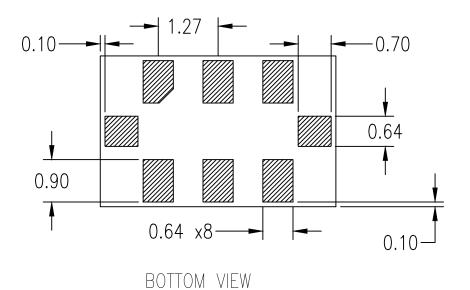
	Package Revision History				
Date Created	Rev No.	Description			
Nov. 12, 2019 00 Initial Release					





5.0 x 3.2 x 0.85 mm Body,1.27mm Pitch LXG8D1, PSC-4857-01, Rev 00, Page 1





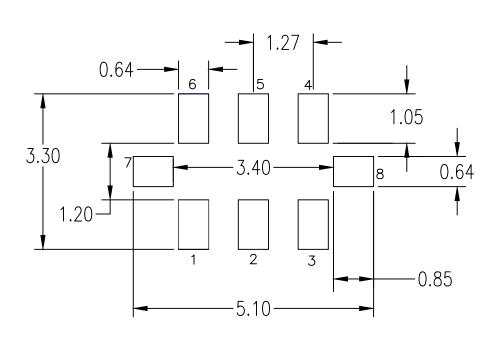
# NOTES:

1. ALL DIMENSIONS IN MM.

# 8-LGA, Package Outline Drawing



5.0 x 3.2 x 0.85 mm Body,1.27mm Pitch LXG8D1, PSC-4857-01, Rev 00, Page 2



RECOMMENDED LAND PATTERN DIMENSION

## NOTES:

- 1. ALL DIMENSION ARE IN MM. ANGLES IN DEGREES.
- 2. LAND PATTERN RECOMMENDATION PER IPC-7351B

  GENERIC REQUIREMENT FOR SURFACE MOUNT DESIGN

  AND LAND PATTERN.

	Package Revision History				
Date Created	Rev No.	Description			
April 22, 2020	April 22, 2020 00 Initial Release				

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(Rev.1.0 Mar 2020)

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